

Transient Voltage Suppressors for ESD Protection

General Description

The LESD8D5.0CB1T5G is designed to protect voltage sensitive components from ESD and transient voltage events. Excellent clamping capability, low leakage, and fast response time, make these parts ideal for ESD protection on designs where board space is at a premium. Because of its small size, it is suited for use in cellular phones, digital cameras and many other portable applications where board space is at a premium.

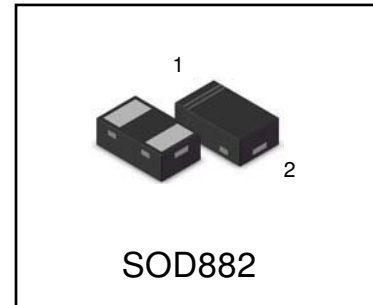
Applications

- Cellular phones
- Portable devices
- Digital cameras
- Power supplies

Features

- Small Body Outline Dimensions
- Low Body Height
- Peak Power up to 85 Watts @ 8 x 20 μ s Pulse
- Low Leakage current
- Response Time is Typically < 1 ns
- We declare that the material of product compliance with RoHS requirements.

LESD8D5.0CB1T5G



Ordering information

Device	Marking	Shipping
LESD8D5.0CB1T5G	U2	10000/Tape&Reel

Absolute Ratings (T_{amb}=25°C)

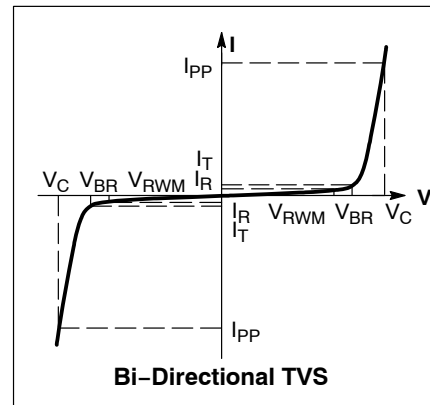
Symbol	Parameter	Value	Units
P _{PP}	Peak Pulse Power (t _p = 8/20 μ s)	85	W
T _L	Maximum lead temperature for soldering during 10s	260	°C
T _{stg}	Storage Temperature Range	-55 to +155	°C
T _{op}	Operating Temperature Range	-40 to +150	°C
T _j	Maximum junction temperature	150	°C
	IEC61000-4-2 (ESD)		
	air discharge	±30	KV
	contact discharge	±30	

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Electrical Parameter

(T_A = 25°C unless otherwise noted)

Symbol	Parameter
I _{PP}	Maximum Reverse Peak Pulse Current
V _C	Clamping Voltage @ I _{PP}
V _{RWM}	Working Peak Reverse Voltage
I _R	Maximum Reverse Leakage Current @ V _{RWM}
V _{BR}	Breakdown Voltage @ I _T
I _T	Test Current
P _{pk}	Peak Power Dissipation
C	Capacitance @ V _R = 0 and f = 1.0 MHz



Electrical Characteristics

Device	V _{RWM} (V)	I _R (μA) @ V _{RWM}	V _{BR} (V) @ I _T (Note 1)		I _T	V _C (V) @ I _{PP} = 1 A	V _C (V) @ I _{PP} = 8 A	I _{PP} (A)	P _{PK} (W)	C (pF)
	Max	Max	Min	Max	mA	Max	Max	Max	Max	Max
LESD8D5.0CB1T5G	5.0	0.5	5.6	8	1.0	8.5	9	10	85	20

*Surge current waveform per Figure 1.

- V_{BR} is measured with a pulse test current I_T at an ambient temperature of 25°C.

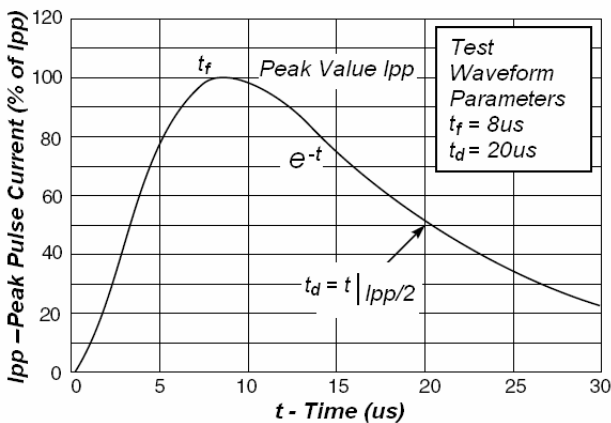


Fig1. Pulse Waveform

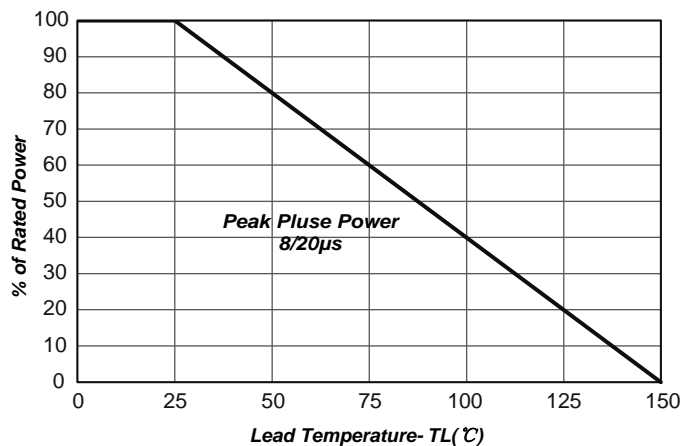


Fig2. Power Derating Curve

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Figure 3. Positive 8kV contact per IEC 61000-4-2

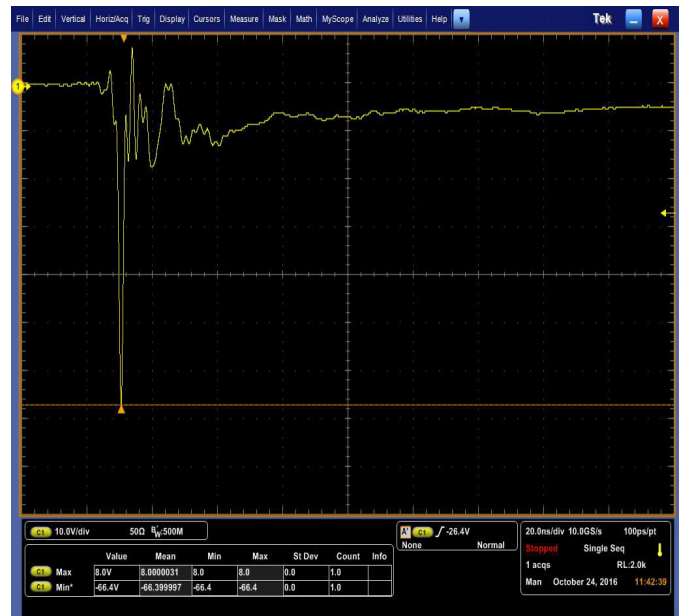


Fig 4. Negative 8kV contact per IEC 61000-4-2

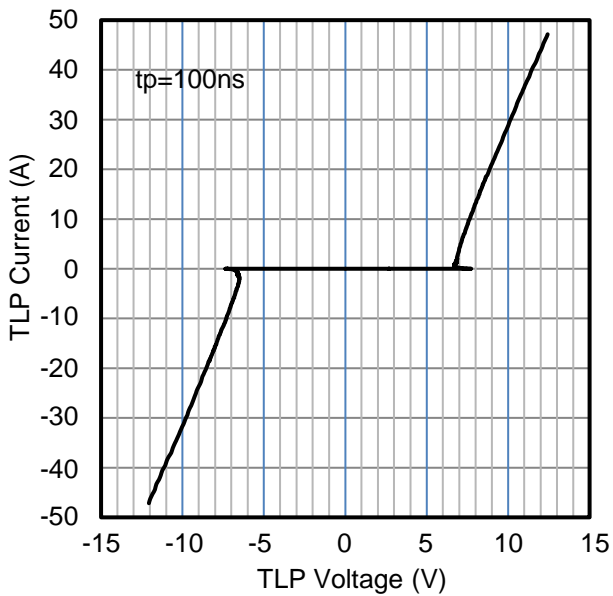
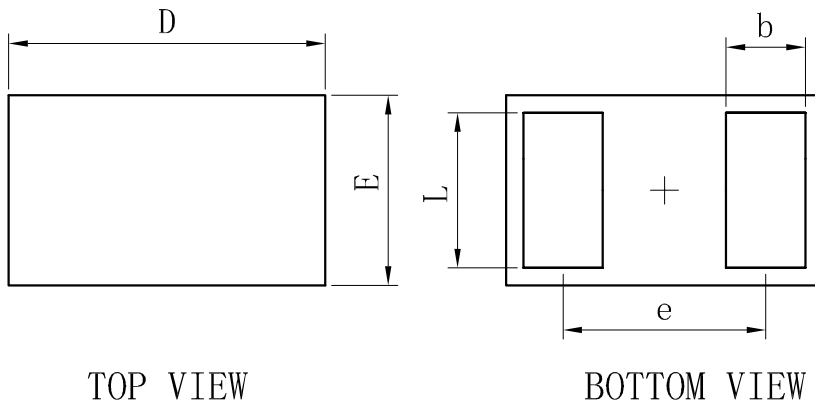


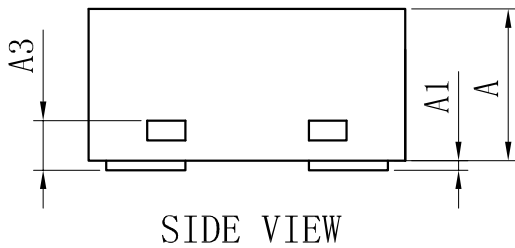
Fig5. TLP Measurement

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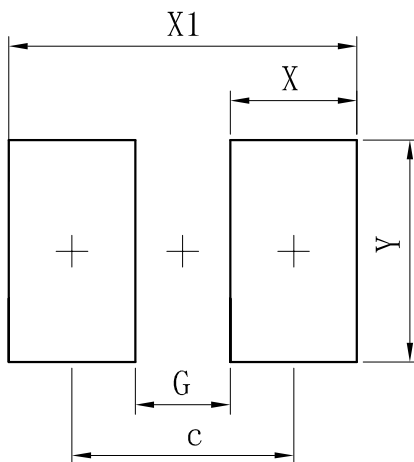
OUTLINE AND DIMENSIONS



SOD882			
Dim	Min	Typ	Max
D	0.95	1.00	1.05
E	0.55	0.60	0.65
e	-	0.64	-
L	0.44	0.49	0.54
b	0.20	0.25	0.30
A	0.43	0.48	0.53
A1	0	-	0.05
A3	0.127REF.		
All Dimensions in mm			



SOLDERING FOOTPRINT



Dimensions	(mm)
c	0.70
G	0.30
X	0.40
X1	1.10
Y	0.70